

Microprocessors and Microcomputer Systems

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Preface

This topical state-of-the-art analysis is an integrated digest of the large volume of information presently available on the subject of digital computers as oriented toward the latest innovations, microprocessor and microcomputer.

With an unpredictably short learning phase covering a total of approximately 25 years of changing technology, the digital computer has swiftly moved at an accelerated pace of development, from the relay to the vacuum tube, from the tube to the discrete solid-state temperature-sensitive germanium transistor, parametrics and tunnel diode, from the discrete transistor to the stable silicon monolithic individual integrated circuit (IC), then from the IC to the small- and medium-scale integration (MSI) of the minis, and finally from the MSI to the high-technology of the mass-produced *large-scale* integrated form of microelectronics, LSI, to present eventually a dedicated powerful Microcomputer-on-a-chip that performs at speeds enhanced by 4 to 5 orders of magnitude—as compared to the original vacuum-tube versions.

With each advance in the reduction of size, the digital computer has achieved progressively higher reliability in operation. With regard to its flexibility and its computation capacity, the microcomputer is more powerful than the first- and second-generation digital computers built during the 1950s to occupy oversized rooms.

The author presents this analysis on the presently available microprocessors and microcomputer systems and the associated LSI hardware and firmware, at a time when the technology of microelectronics is fairly well established. The various topics in the text are chosen in order to facilitate communication between not only hardware and software specialists, but also marketing and training personnel. In view of the unavoidable terminology involved, two complete readings are recommended for a better grasp of the hardware and software terms.

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iv Preface

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List of Illustrations

1

Fig. 1-1. Architecture of a typical microprocessor.	3
Fig. 1-2. A typical microcomputer system.	4
Fig. 1-3. Organization of a typical minicomputer.	6

2

Fig. 2-1. Nuclei of silicon atoms (with inner K and L shells of electrons) in intrinsic single-crystal silicon. Covalent bonds are formed by the four free valence-electrons of adjacent atoms. Controlled "doping" of an atom of impurity will introduce either a "donor" electron or an "acceptor" hole amid the covalent bonds for NMOS and PMOS, respectively.	17
Fig. 2-2. Energy levels in semiconductors.	17
Fig. 2-3a. PMOS, NMOS, CMOS—The basic logic building-block, "inverter" of LSI.	23
Fig. 2-3b. TTL, ECL/EFL—The basic logic building-block, "inverter" of MSI.	24
Fig. 2-3c. I ² L, different versions—The basic logic building block "inverter".	26
Fig. 2-3d. Extension of a two-input complementary MOSFET NOR-Gate as a building-block to R-S storage flip-flop.	28
Fig. 2-4(a-h). Charge-coupled devices (CCD).	30-33
Fig. 2-4a. Three-phase CCD "depletion" condition (three-phase clock pulses applied).	30
Fig. 2-4b. CCD: "Storage" condition.	30
Fig. 2-4c. CCD: "Transfer" mode.	30
Fig. 2-4d. CCD: Two-phase device; charge transfer.	30
Fig. 2-4e. Buried-gate CCD.	30
Fig. 2-4f. CCD as a sophisticated full-adder and shift register.	31
Fig. 2-4g. CCD as an image-sensing device for television (three versions).	32
Fig. 2-4h. Bell Laboratories CCD video camera, Research version: vertical transfer system; 128 X 106 elements, 3 X 5 mm.	33
Fig. 2-5. MESFET (metal semiconductor field-effect transistor): High-speed and low-power versions.	34

vi List of Illustrations

Sec. 2-8.7.	Tristate TTL.	28
Sec. 2-11.	Bi-FET monolithic sample-and-hold IC (BIMOS).	35
3		
Fig. 3-1a.	Static random-access read/write RAM memory.	39
Fig. 3-1b.	Dynamic random-access read/write RAM memory.	40
Fig. 3-1c.	8,192-bit static read-only memory (ROM).	41
Fig. 3-1d.	Bipolar PROM (1,024-bit: 256 X 4).	42
Fig. 3-2.	Static NMOS RAM, tristate output buffers (256 X 4 bit).	44
Fig. 3-3.	Latest high-density RAM main-memory, MOSTEK-MK4116, 16-K bit (volume production). Eight 16-pin chips to provide 16-K byte main memory.	46
Fig. 3-4.	RALU (Register Arithmetic Logic Unit).	47
Fig. 3-5.	Content Addressable Memory (CAM) system organization.	48
Fig. 3-6.	CCD Line-Addressable RAM (LARAM: Fairchild).	49
Fig. 3-7.	Organization of 65,384-bit CCD RAM.	51
Fig. 3-8.	Organization of Metal-Nitride-Oxide Semiconductor MNOS "Non-Volatile" Memory.	53
Fig. 3-9.	Nippon "Non-Volatile" 8-K Bit Electrically-Erased EPROM ("FAMOS" memory).	54
Fig. 3-10.	The amorphous semiconductor memory.	55
4		
Fig. 4-1.	Magnetic CORE—Four cells in the Bit-Plane of a 3-D, 3-Wire Type Core-Memory.	57
Fig. 4-2.	Magnetic tape—Data record on 7/9-Track Tape.	59
Fig. 4-3.	RZ, NRZM tape recording.	60
Fig. 4-4.	Types of Memory, and Access-Time (Cost/Bit).	60
Fig. 4-5.	Typical interface of microcomputer to peripheral controller.	62
Fig. 4-6.	Magnetic bubble-memory, on-the-card mass-storage for a microcomputer-on-a-card.	64
6		
Fig. 6-1a.	Typical interface "hand-shake" signals of a computer and a peripheral device. Pulse waveform timings.	71
Fig. 6-1b.	Bipolar "high-speed" microcontroller (MPU) timings (compatible to latest high-speed CPU timings).	72
Fig. 6-2.	I/O-bus and peripheral devices.	73
Fig. 6-3.	A typical open-collector, three-input, 4-bit digital multiplexer. (TTL MSI-chip; analogous to four-pole, three-position switch). Type 8263, Signetics.	75
Fig. 6-4.	A typical two-input, dual four-output decoder/demultiplexer. Types 10171 and 8235, Signetics.	76
Fig. 6-5.	A simple 2-bit diode decoder.	77
Fig. 6-6.	I/O-bus interface data for several peripherals.	78
Fig. 6-7.	LSI interface, Intel type 8251 (for USART serial communication interface, EIA, RS-232-C). LSI chips used in Intel Systems types MCS-80 and MCS-85.	79
7		
Fig. 7-1.	Intel MCS-80 microcomputer system.	82
Fig. 7-2a.	Organization of Intel SBC 80/10 microcomputer on a card.	84
Fig. 7-2b.	Intel 8048 microcomputer on a chip.	85
Fig. 7-3.	Organization of the CPU of LSI-11.	88
Fig. 7-4.	The F-8 microcomputer.	89
Fig. 7-5.	Application of F-8 in a surveillance receiver.	91
Fig. 7-6.	Comparative architecture of MC-6800 and Intel 8080.	92
Fig. 7-7.	Signetics Type 2650 microprocessor (Si-gate NMOS, ion-implanted).	96
Fig. 7-8a.	Intersil CMOS IM-6100 system organization.	98
Fig. 7-8b.	Architecture of Intersil IM-6100.	99
Fig. 7-9.	IBM-5100 "Portable Computer."	101
Fig. 7-10.	System organization of IBM-5100 portable computer.	102
Fig. 7-11.	Architecture of the basic TMS-1000 microprocessor.	104
Fig. 7-12.	TMS-990/4 microcomputer system, using the Texas Instruments 9900 (8080A).	105

Fig. 7-13.	SBP-0400A microprocessor (Texas Instruments); "bit-slice" technique.	106
Fig. 7-14.	Z-Log, Z-80, microprocessor.	108
Fig. 7-15.	Architecture of IMP-16, National Semiconductor. PMOS slices are used for CPU and CROM along with TTL circuits.	111
Fig. 7-16.	System-20 microcomputer with SMS-300 microcontroller.	113
Fig. 7-17.	Application of the RCA Avionics, SCP-234 microcomputer system for attitude-control.	116
Fig. 7-18.	Intel 8080A (ruggedized to meet Defense standards).	117

8

Fig. 8-1.	Organization of a time-share system.	121
Fig. 8-2.	Hierarchical and distributed networks.	122
Sec. 8-23.	Peripheral interface of a microcontroller system.	133
Fig. 8-3a.	Microprogram-controlled processor.	140
Fig. 8-3b.	Typical microprogramming subsystem.	141
Sec. 8-33.	Flowchart, iterative procedure.	143
Fig. 8-4.	Symbolic blocks used in flow-charts.	143
Sec. 8-33.	Flowchart, addition and subtraction in 10's complement notation.	144
Fig. 8-5.	MPU flowchart, MC-6800.	146
Fig. 8-6.	Processor bus-interface, MC-6800.	147
Fig. 8-7.	Typical microprocessor system development, hardware/software.	152

10

Fig. 10-1.	Typical operating console of a mini or microcomputer.	162
Fig. 10-2.	Bus-oriented architecture.	163
Fig. 10-3.	"Race conditions," waveform timings.	165
Fig. 10-4a.	Field programmable logic array (FPLA).	166
Fig. 10-4b.	Programmable logic array (PLA).	166
Fig. 10-5.	PLA and ROM techniques.	167
Fig. 10-6.	Custom-wired FPLA, bipolar version.	168
Fig. 10-7.	Two-phase dynamic MOS shift-register with two-phase nonoverlapping clock pulses.	170
Fig. 10-8.	SC/MP "Kitbug" (economy keyboard-display peripheral device used to interface with SC/MP microcomputer system).	174
Fig. 10-9.	"Calculator" key-board-display system—Interface for SC/MP microcomputer.	175
Fig. 10-10.	"VRAM-converter" for black-and-white or color television monitor or receiver.	179
Fig. 10-11 (a-z).	Basic Circuit Concepts of Digital Logic.	180
Fig. 10-11a.	Logic, Inverter (positive and negative logic).	180
Fig. 10-11b.	AND/NAND (positive and negative logic).	180
Fig. 10-11c.	OR/NOR—(Inclusive-OR) (positive and negative logic).	180
Fig. 10-11d.	Exclusive-OR.	180
Fig. 10-11e.	Equality Gate.	181
Fig. 10-11f.	Three-variable switching function.	181
Fig. 10-11g.	Exclusive-OR, realization with Nand gates.	181
	Equality gate, realization with Nor gates.	181
Fig. 10-11h.	"Dissent" logic.	181
	"Majority voter" logic.	181
Fig. 10-11i.	Three-variable function with 4-input multiplexer (combinational logic).	182
Fig. 10-11j.	R-S flip-flop (Set-Reset).	182
Fig. 10-11k.	R-S storage flip-flop—clocked R-S (RST) flip-flop.	182
Fig. 10-11l.	J-K flip-flop.	183
Fig. 10-11m.	Master-slave flip-flop.	183
Fig. 10-11n.	Toggle flip-flop.	184
Fig. 10-11p.	Delay flip-flop.	184
Fig. 10-11q.	One-shot or single-shot multivibrator or "monostable multi."	185
Fig. 10-11r.	Astable multivibrator (MV).	185
Fig. 10-11s.	Schmitt-trigger.	185
Fig. 10-11t.	Storage register.	186

viii List of Illustrations

Fig. 10-11u.	4-bit parallel access shift register.	187
	4-bit monolithic shift register (TTL, MSI). Parallel-IN, Serial-OUT (54/7494—Signetics).	188
Fig. 10-11v.	Half and full-adders—Truth table (3-bit full adder).	
	Binary parallel adder (4-bit).	
	Binary serial adder.	189
Fig. 10-11w.	Full subtractor.	
	Subtractors used for divider.	190
Fig. 10-11x.	Multiplication: repeated addition.	
	Division: (subtraction and shifting).	
	Analog-to-digital (A/D) Converter (binary encoder).	
	Digital-to-analog (D/A) Converter.	191
Fig. 10-11y.	Binary decade counter (waveforms).	
	Decade-to-binary coded decimal (BCD) count, decoder.	192
Fig. 10-11z.	Switching algebra.	192
Sec. 10-13.6.	Propagation delay, rise-time and fall-time.	193
	Slewing rate.	194
Sec. 10-13.7.	Schottky or hot-carrier barrier diode.	194
Sec. 10-13.19.	PNPN switching device (four-layer diode), and thyristor (silicon controlled rectifier—SCR).	196
Fig. 10-12.	Symbolic representation of diodes, transistors, etc.	197

11

Fig. 11-1.	Typical data communications channel.	200
Fig. 11-2.	Line monitor for an interface.	203
Fig. 11-3.	Ack-Nack "store-and-forward" transmission.	204
Fig. 11-4.	Radar video/pulse digitizing system.	206
Fig. 11-5.	Hybrid 10-bit, 1- μ s A/D converter.	207
Fig. 11-6.	Data Devices DAC-3 D/A converter.	207
Fig. 11-7.	Fiber-guide (Fiber-Optics cable).	208
Fig. 11-8.	"Teletext" captioning, system block-diagram.	209
Fig. 11-9.	Typical FDM-system.	210
Fig. 11-10.	Typical TDM data packets.	211
Fig. 11-11.	Forward-transmission, "ARQ" network transmission.	212
Fig. 11-12.	Automobile application with two microprocessor chips.	213
Fig. 11-13.	Telephone Network, using TDM electronic switching system.	215
Fig. 11-14.	Telephone microcomputer switching center.	216
Fig. 11-15.	Architecture of a typical "calculator" chip.	217
Fig. 11-16.	"Hypercube" architecture of Microcomputers.	218
Fig. 11-17.	Motorola microprocessor analyzer display, MPA-1.	220
Fig. 11-18.	H.P. automatic stimulus-response testing concept.	220
Fig. 11-19.	Hybrid automatic testing system (General Dynamics).	221

12

Fig. 12-1.	Optically-coupled isolator with LED for remote control.	224
Fig. 12-2.	Strobed optically-coupled isolators.	225
Fig. 12-3.	Magnetic bubble displays.	227
Fig. 12-4.	Fixed-format refreshed CRT-display system.	228
Fig. 12-5.	"Refresh" graphics CRT-display system.	229
Fig. 12-6.	Vector generator and dot-character generator.	230
Sec. 12-5.	Character generation of ASCII code (7 X 9 format).	231
Fig. 12-7.	Microprocessor-controlled CRT-terminal.	232

13

Fig. 13-1.	MTBF versus "component life in years."	235
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APPENDIX A

Fig. A-1. Junction FET, N-and-P channel types.	242
Fig. A-2. Junction FET and transistor characteristics.	242
Fig. A-3. Equivalent circuits (low-freq. and high-freq.).	243
Fig. A-4. "Triode and tetrode"—connected JFETs; "pinch-off."	244
Fig. A-5. JFET, depletion mode—N-and P-channel types.	244
Fig. A-6. MOSFET: Comparative characteristics—depletion and enhancement modes.	246
Fig. A-7. Depletion-and enhancement-mode configurations of MOSFET.	247
Fig. A-8. Thin-film-transistor MOSFET characteristics.	249
Fig. A-9. MOSFET, equivalent circuit (common source).	250

APPENDIX B

Fig. B-1. Original discrete PNP-NPN circuit configuration of I^2L signal processing, 1960. (Actual circuit used in the production run of RCA quadruplex color videotape recorders).	254
Fig. B-2. "Avalanche serial PNP-NPN" push-pull output stage. High-sensitivity low-current power-output circuit for high-speed position servo.	255

APPENDIX C

Fig. C-1. Typical 12-channel satellite transponder.	260
Fig. C-2. Digitized real-time global color-television transmission via satellites.	261

List of Tables

Table 1-1. Present status of digital computers	8
Table 2-1. A "window" on the Periodic Table	11
Table 2-2. "Free valence electrons" of the atoms of interest	13
Sec. 2-8.6. Comparison of Bipolar TTL and I ² L	27
Table 3-1. Types of RAM memory and possible density on chip	44
Sec. 6-1. Some of the preferred standards for the transmission of data to a digital computer	72
Table 7-1. Instruction formats—Signetics, type 2650 Microprocessor	94, 95
Sec. 8-2. Types of Software	121
Sec. 8-4. Conventional numbering of bits in a digital computer	123, 135
Sec. 8-26. Cross-software	136
Table 8-1. Typical Instruction set of a Microprocessor	145
Table 8-2. Table of common codes	148
Sec. 8-35.4. Binary and Gray codes	149
Tables 9-1 through 9-6. Comparative reference data—Microprocessors and Microcomputer systems	155-160
Table 10-1. Basis of software for the Keyboard-Scan (National Semiconductor)	174
Table A-1. Comparison of MOS/LSI processing techniques	251

Contents

Preface	iii
List of Illustrations	v
List of Tables	x
1. INTRODUCTION TO MICROPROCESSORS AND MICROCOMPUTER SYSTEMS	1
1-1 Scope	1
1-2 Architecture	2
1-2.1 An Introductory Example of the Architecture of a Microprocessor	5
1-3 Microcomputer Architecture Compared to Minicomputer Architecture	5
1-4 Present Status of Digital Computers	8
2. LARGE-SCALE INTEGRATION (LSI)	10
2-1 Fundamentals in Brief: Semi-Conductor Physical Chemistry	10
2-1.1 Quantum Theory and Electron	10
2-1.2 Periodic Classification of Elements and Silicon	12
2-1.3 Carbon and Diamond	12
2-2 Silicon, the Choice Semiconductor Material	14
2-2.1 Silicon	15
2-2.2 Valence and Conduction Bands	16
2-2.3 Summary	18
2-3 Monolithic Fabrication (Small-, Medium-, and Large-Scale Integration)	19
2-4 Analog/Linear Integrated Circuits (ICs)	20
2-5 Thin-Film Fabrication	20
2-6 Thick-Film Fabrication	20
2-7 Hybrid Technology	21
2-8 The LSI Solid-State Technology Applicable to the Microcomputer Systems	21
2-8.1 PMOS/NMOS (P&N-Type Metal-Oxide-Semiconductor)	22
2-8.2 CMOS (Complementary Symmetry Metal-Oxide-Semiconductor MOSFET)	22
2-8.3 TTL/STTL (Transistor-Transistor-Logic/Schottky-)	23

xii Contents

2-8.4 ECL/EFL (Emitter Coupled Logic/Emitter Function Logic)	24
2-8.5 I^2L /Low-Power Schottky I^2L (Integrated Injection Logic)	25
2-8.6 Comparison of TTL and I^2L , High-Speed Bipolar LSI Technology	27
2-8.7 Tri-State TTL	27
2-8.8 Silicon-on-Sapphire CMOS	27
2-9 Charge-Coupled Devices (CCD)	28
2-10 GaAs FET RF Microwave Amplifiers (Gallium-Arsenide Field-Effect Transistors)	32
2-11 Bi-FET Monolithic Sample/Hold IC (BIMOS)	34
2-12 MESFET (Metal Semiconductor Field-Effect Transistor)	36
3. SOLID-STATE LSI MEMORIES	37
3. Solid-State LSI Memories	37
3-1 ROM/PROM/EPROM, EAROM (Read Only Memory, Programmable ROM)	37
3-2 Random Access Memories (RAMs), Static and Dynamic	39
3-3 Register and Arithmetic Logic Unit (RALU)	45
3-4 Content Addressable Memory (CAM)	47
3-5 LSI CCD Memories (Bucket Brigade Devices)	49
64-Kilobit CCD Memory (RAM)	50
3-6 Magnetic Bubble Memory (MBM)	50
3-7 Electron-Beam Addressable Memory (EBAM) or Beam-Addressable MOS Memory (BEAMOS)	51
3-8 V-MOS (Vertical-Notch MOS)	51
3-9 D-MOS (Depletion-Mode-MOS)	52
3-10 "Non-Volatile" MNOS (Metal Nitride Oxide Semiconductor) Memory and Floating-Gate Memories (FAMOS)	52
3-11 I^2L Memory and Microprocessors	53
3-12 Amorphous Semiconductor Memory (OVANICs)	55
4. MASS-MEMORY LIBRARIES FOR MICROCOMPUTER SYSTEMS	56
4-1 The Present High-Speed Auxiliary On-Line Memory, CORE	56
4-2 Magnetic Disc and Flexible Floppy Disk	57
4-3 Tape Cartridge. Tape Coding (7-ch. Tape Pattern) RZ and NRZ Tape Data Recording	58
4-4 Types of Memory Versus Access Time	60
4-5 Peripheral Interface for Tape Cassette or Floppy Disk	61
4-6 Magnetic "Bubble" Mass-Memory (MBM)	61
5. MEMORY TRANSFER VIA INTERNAL REGISTERS	66
5-1 Introduction to Registers	66
5-2 General-Purpose Registers (GPRs)	67
5-3 Accumulator Register (A or B)	67
5-4 Scratch-Pad Memory	68
5-5 Stack-Pointer (SP)	68
5-6 Direct Memory Address	68
5-7 Program Counter Register (PC)	68
5-8 Cache-Memory (Data General)	68
5-9 FIFO (First-In-First-Out) Memory	69
LIFO (Last-In-First-Out) Memory—(page 68, 5-5)	
5-10 DMA (Direct Memory Access Technique)	69
6. INPUT/OUTPUT INTERFACE	70
6-1 Input/Output Interface; Typical Digit Data	70
6-2 Built-In I/O Section of a Microprocessor	73
6-3 Multiplexer or Multiplexer Channel (Polling)	74
6-4 Decoder/Demultiplexer	74

6-5	Users Line I/O Bus Interface	78
6-6	Programmable Peripheral Interface of Intel	78
7.	LSI MICROPROCESSORS AND SINGLE-CHIP MICROCOMPUTERS	81
7-1	Description of Some Chips Available Off-the-Shelf	81
7-2	Intel-8080	81
7-2.1	Intel N-Channel Microprocessor: 8080 with Intellec-8 Program Development Facility	81
7-2.2	Intel SBC 80/10 Microcomputer-on-a-Card	83
7-2.3	Intel 8748/8048 Microcomputer-on-a-Chip	86
7-3	PDP-11-03 Microcomputer, Dig. Equipment Corp.	87
	LSI-11, Microcomputer Operating System	87
7-4	Type 3850, Fairchild Microcomputer Systems, (F-8 Microcomputer)	88
7-5	Exorciser (Motorola MC6800)	91
7-6	AMI-6800, American Microsystems Inc.	91
7-7	Signetics-2650 Microprocessor (North American Philips)	93
7-8	PPS-4/1 and PPS-8, Rockwell International	97
7-9	CDP-1801, COSMAC Microcomputer (2-Chip), RCA	97
7-10	Intersil IM-6100	98
7-11	IBM-5100 "PORTABLE COMPUTER"	100
7-12	General Instruments Series-1600 Microprocessor	102
7-13	MCP-1600, Western Digital Corp.	103
7-14	TMS-1000 Series, Texas Instruments	103
	T.I. TMS-9900 (NMOS-8080) Microcomputer System	103
	T.I. SBP-0400A Bipolar (I^2L) 4-Bit Microprocessor; "Bit-Slice" 16-Bit Microcomputer	104
	T.I. 9440, 16-Bit Bipolar I^2L Microprocessor	106
7-15	Zi-Log Z-80 Microprocessor, Exxon (Second Source, Mostek)	107
7-16	Data General mN-601 Microprocessor	109
7-17	Miproc-16, 16-Bit Microcomputer System, Plessey	109
7-18	IMP-16 National Semiconductor	110
7-19	Custom Microprocessor, Advanced MicroDevices AM-2900 Microprocessor (Multi-Chip)	110
7-20	Scientific Microsystems, System-20; SMS-300 Microcontroller	112
7-21	Latest Microcomputer Systems Meeting Defense Standards: A Typical Ruggedized Microcomputer	114
7-22	RCA Avionics CMOS, SCP-234 Microcomputer System	115
7-23	Intel M8080A Microprocessor (A Ruggedized Version)	116
7-24	Rolm AN/AYK-28 (16/64) Microcomputer System	118
7-25	Summary	118
8.	SOFTWARE AND FIRMWARE	119
8-1	The Software Procedure in Microcomputer Systems	119
8-2	Time-Share Computer Services	120
8-3	Prototyping Systems	121
8-4	Memory Organization, Virtual Memory, Bootstrap Loader	122
8-5	Assembler, Macro-Assembler	124
8-6	Compiler for High-Level Languages such as Fortran, and Basic	124
8-7	Interpreter	125
8-8	Debugging a Program	125
8-9	Text-Editor	126
8-10	Linkage Editor	126
8-11	Batch-Processing	126
8-12	Stack-Interrupt Processing	126

xiv Contents

8-13	Software Trends	127
8-14	High-Level Language, Basic	127
8-15	High-Level Language, APL	128
8-16	Cobol (Common Business Oriented Language)	128
8-17	PL/1 (Programming Language/One); ALGOL and PASCAL	129
8-18	Fortran (Data-General NOVA), DEC 8-K Word Fortran	130
8-19	Routine Software Needs	130
8-20	Executive Program, Disk Operating System (DOS)	131
8-21	Real-Time Operating System	131
8-22	Interface Adapter	132
8-23	Peripheral Interface of a Microcomputer System	132
8-24	Addressing Modes	133
8-24.1	Direct Addressing	133
8-24.2	Indirect Addressing	134
8-25	Number of Instructions in a Microcomputer System	134
8-26	Cross-Software	136
8-27	ROM/PROM Emulation	136
8-28	Vectored Interrupt	137
8-29	Graphics (Computer)	138
8-30	Multi-Tasking and Multi-Programming	138
8-31	Microprogramming Approach	139
8-32	Fast Fourier Transform, FFT	141
8-33	Flow-Chart and Programming	143
8-34	Vendor's Information on Microprocessors	145
8-35	Glossary of Common Software Terms	147
8-35.1	Bit, Byte, Character, Word, BCD, Baud, Flag, Statistical Data, Word Length, I/O Bus Lines, Parity-Bit, EBCDIC	147
8-35.2	Table of Common Codes and Parity-Bit	148
8-35.3	Error-Correcting Codes	149
8-35.4	Unit-Distance Codes	149
8-35.5	Fetch (Phase); Execute (Phase), Interrupt (Phase)	150
8-35.6	IRG (Inter Record Gap)	150
8-35.7	Macro-Instruction Versus Microinstruction	150
8-35.8	Base-Page	150
8-35.9	PSW (Program Status Word)	150
8-35.10	Relocatable Loader and Relocatable Memory	150
8-35.11	Linking Loader/Editor	150
8-35.12	Jump Conditions	151
8-35.13	Cycle-Time and Cycle-Stealing	151
8-35.14	Single and Multi-Address Machines	151
8-35.15	Fixed and Variable Field-Length	151
8-35.16	Fixed Point and Floating Point	151
8-35.17	File/Record	151
8-35.18	Real-Time	151
8-35.19	Subroutine	152
8-35.20	Diagnostic Programs	152
8-35.21	Micro-Assembler	153
8-35.22	Typical Microprocessor System Development, Hardware and Software	153
9.	REFERENCE DATA ON THE MICROPROCESSORS AND MICROCOMPUTER SYSTEMS (TABULAR FORMAT)	154
Table	Abbreviations Used in the Tables	154
9-1.1	IBM-5100	155
9-1.2	DEC, LSI-11	155

9-1.3	RCA CDP-1801	155
9-1.4	Intel, 4004	155
9-1.5	Intel, 8080(A)	155
9-2.6	Intersil, IM-6100	156
9-2.7	Microcomputer Associates, 6502	156
9-2.8	Mostek, 5065	156
9-2.9	Fairchild Microsystems (F-8)	156
9-2.10	General Instrument Corporation, CP-1600A	156
9-3.11	Motorola Semi-Conductor, MC-6800	157
9-3.12	National Semi-Conductor, IMP-8/16 (NMOS)	157
9-3.13	National Semi-Conductor, Scamp-PMOS	157
9-3.14	Plessey Microsystems, Miproc-16	157
9-3.15	Intel On-Chip Microcomputer, MCS-48	157
9-4.16	Rockwell International, PPS-8	158
9-4.17	Scientific Microsystems, SMS-300	158
9-4.18	Texas Instruments, TMS-9900 (990-4)-NMOS (8080A)	158
9-4.19	T.I. SBP-9440 (I ² L-16 Bit)	158
9-4.20	T.I. SBP-0400A (I ² L-4 Bit)	158
9-5.21	Signetics Corporation, 2650	159
9-5.22	NEC Microcomputers, μ PD-8080D	159
9-5.23	Electronics Arrays, EA-9002	159
9-5.24	Advanced Micro-Devices, AM-2900, 16-Bit, using RALU (Register Arithmetic Unit)	159
9-5.25	Zilog, Z-80	159
9-6.26	MOS Tech. Inc., MCS-6602/6612	160
9-6.27	MicroNova, μ Nova	160
9-6.28	Essex International, Sx-200	160
9-6.29	General Instruments, AEG (Germany), SGS (Italy), 8000	160
9-6.30	Mostek, 3870	160
10.	MICROPROCESSOR-ASSOCIATED HARDWARE	161
10-1	Hardware In General	161
10-2	Operating Console of a Typical Mini or Microcomputer	162
10-3	Bus-Oriented Architecture	162
10-4	Buffers	163
10-5	Arithmetic and Logic Unit, ALU; "RACE" Conditions	164
10-6	Programmable Logic Array, PLA	165
10-7	2-Phase Non-Overlapping Clock, Multi-Phase Clock Pulses	169
10-8	Microcomputer Peripherals: Punched Card, Card Reader, Line Printer, Paper-Tape, Mag. Tap and CRT K-B, Video RAM	171
10-9	A Custom Single-Card Microcomputer Subsystem	173
10-10	"SC/MP", National Semiconductor "Kitbug" Keyboard Scan	173
10-11	Programming Accessories; μ Pro-80 Microcomputer Development System and VRAM-Television Monitor-Display	175
10-12	Basic Circuit Concepts of Digital Logic (a through z)	180
10-13	Glossary of Hardware Terms	193
10-13.1	Timings Encountered in Microcomputer and Microwave Fields	193
10-13.2	Batch-Processing of Microprocessors	193
10-13.3	Flag	193
10-13.4	Logic-Clip	193
10-13.5	Bit-Plane	193
10-13.6	Propagation-Delay, Rise-Time, Fall-Time Slewing-Rate	193
10-13.7	Schottky	194
10-13.8	Boolean Algebra	194

10-13.9	Sample-&-Hold	194
10-13.10	Analog Voltage Comparator	195
10-13.11	"Don't Care" Condition	195
10-13.12	Min and Max Terms	195
10-13.13	Latch	195
10-13.14	Modulo-2 ⁿ	195
10-13.15	Redundancy	195
10-13.16	Reliability	195
10-13.17	Hall-Effect (Solid-State Relay)	196
10-13.18	Gunn-Effect (Gunn-Diode)	196
10-13.19	PNPN Switching Device and Silicon Controlled Rectifier (SCR)	196
10-13.20	Thin and Thick-Film Resistors and Capacitors	196
10-13.21	Voltage-Variable Capacitors and Varactors	198
10-13.22	P-i-N Diode	198
10-13.23	Symbolic Representation of Diodes and Transistors	198
11.	APPLICATIONS OF MICROPROCESSORS	199
11-1	Applications of Microprocessors in Data Communications Networks	199
11-2	The EIA-Standard RS-232C Interface	201
11-3	Polling Procedures	202
11-4	Line Monitor	203
11-5	Some Communications Networks in Operation	203
11-6	Ack-Nack Store and Forward Transmission of Data	204
11-7	Computer Aided Services (CAD and Monte Carlo Simulation)	204
11-8	High-Speed Data Acquisition and Processing with A/D, D/A Converters	206
11-9	Low-Loss Fiber-Optic Waveguides for Multiplexed Data Communications	208
11-10	Tele-Text or Captioning on a Dedicated TV Cable	208
11-11	FDM and TDM in Data Communications	210
11-12	Data Communications by Forward Transmission	211
11-13	PCM (Pulse Code Modulation)	212
11-14	Automotive Microprocessor Applications	213
11-15	Telecommunications, Electronics Switching Systems	214
11-16	MOS-LSI Single-Chip Calculator	216
11-17	H.P. 9825 Programmable Desk-Top Professional Calculator	217
11-18	Micro/Minicomputers Versus Large-Scale Computers, "Hyper-Cube" Systems	218
11-19	H.P. Logic-State Analyzer, Model 1600A/1607A, Motorola Microprocessor Analyzer, MPA-1	219
11-20	Automatic Test Systems (ATS)	220
11-21	List of Typical Applications of Microprocessors	222
12.	DISPLAYS: SOLID-STATE, GAS-DISCHARGE, AND CRT	224
12-1	LEDs (Light Emitting Diodes) and Light Detectors	224
12-2	LCDs (Liquid Xtal Displays)	226
12-3	Magnetic Bubble Displays	227
12-4	CRT Display, (Graphics)	227
12-5	Commercial Models of CRT Display or Video Display Terminal (VDT)	231
12-6	A Typical Microprocessor-Based On-Line CRT Display Terminal (Matsushita)	231
12-7	Plasma-Gas Display	233
13.	RELIABILITY OF MSI/LSI MICROPROCESSORS	234
13-1	Reliability of MSI and LSI Microprocessors	234
13-2	Automatic Test Procedures	236
13-3	Typical Production Test Procedure	236
13-4	FMECA (Failure Mode Effects and Criticality Analysis of Defense Hardware), ARP-926	236